Abstracts

Advanced Monolithic Packaging Concepts for High Performance Circuits and Antennas

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Unwanted electromagnetic coupling between neighboring elements is a common problem in high frequency planar circuits. This paper reports on the elimination of cross-talk in planar circuits using conformal micromachined packaging. In the 5 to 30 GHz range, a back-to-back right-angle bend in microstrip has cross-coupling as high as -20 dB. The use of monolithic packaging concepts reduces this coupling by as much as 20-30 dB down to the noise level of the measurement system.

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